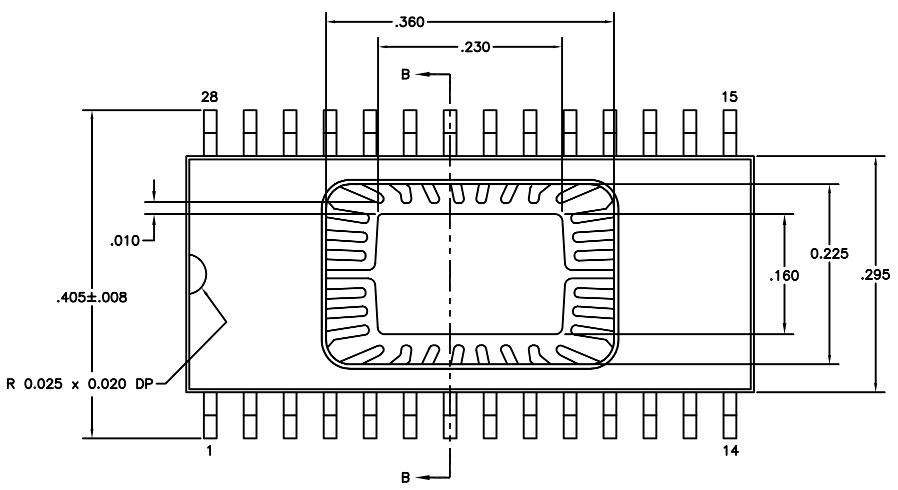
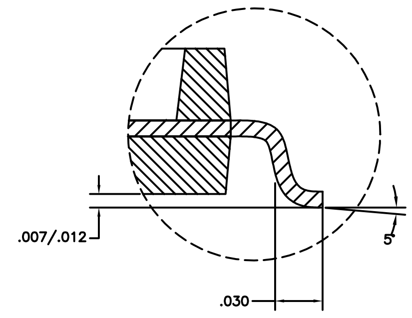
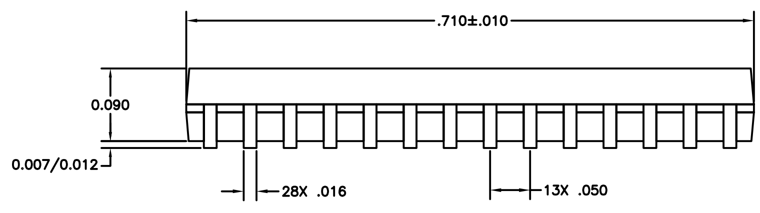
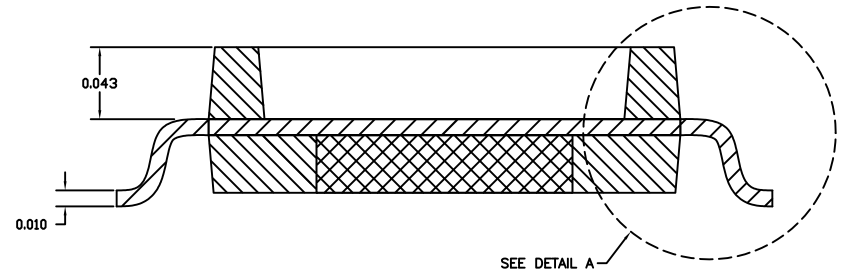
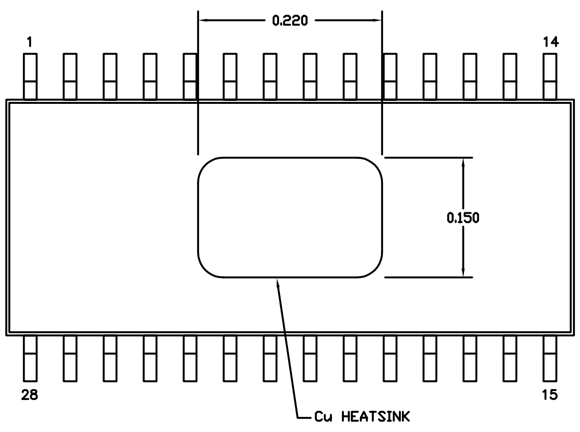
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10797	11/02/06	PRODUCTION RELEASE	D.BENANDO











NOTES:

1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
2. LEADFRAME: COPPER, 194 FH.
3. LEAD FINISH: FULL Au PLATE.
4. FRAME THICKNESS: 0.010±0.001.
5. DIE PAD: 0.220" x 0.160".
6. HEATSINK: COPPER 194 FH 0.210" x 0.140"±.006
7. JEDEC OUTLINE: MS-013.

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE:
X.XX ± 0.01 X.XXXX ±---
X.XXX ± 0.005 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY C. CRUZ DATE 11/02/06
APP BY P. FLASKERUD DATE 11/02/06
CUSTOMER ---

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28 Lead 300 mils SOIC Open-Pak (Heat Enhanced)

SIZE A PART NO. SOIC300-28-OP-01H REV 3
SCALE NONE CAD FILE SOIC300-28-OP-01H-R3.DWG SHEET 1 OF 1

BORDER-AHI-1.DWG
REV 1 ECN 10598